

Title (en)

ELECTRICAL CIRCUIT FABRICATION APPARATUS AND METHOD.

Title (de)

VERFAHREN UND VORRICHTUNG ZUR HERSTELLUNG ELEKTRISCHER SCHALTUNGEN.

Title (fr)

PROCEDE ET APPAREIL DE FABRICATION DE CIRCUITS ELECTRIQUES.

Publication

EP 0231363 A4 19880823 (EN)

Application

EP 86905112 A 19860724

Priority

- US 75946785 A 19850726
- US 88068886 A 19860701

Abstract (en)

[origin: WO8700721A1] Wire (11) for repairing or changing circuit elements such as printed circuits has heat-resistant insulation surrounded by a hot-melt adhesive. The wire is attached to the surfaces of printed circuit boards easily by applying a hot iron (19) to the adhesive layer on the wire and melting the adhesive which then adheres to the board surface. The hot iron has a tip with a groove in it so that when the iron tip is pressed onto the wire, the tip embraces the wire to melt the adhesive quickly and to make the bond relatively quickly. The coating is applied by passing insulated wire vertically through a length of molten adhesive and then through a die.

IPC 1-7

H05K 3/10; C09J 7/02; B32B 15/00; B32B 31/00; B05D 5/12; H05B 1/00; H05B 3/42

IPC 8 full level

H05K 3/22 (2006.01); **H05K 7/06** (2006.01); **H05K 3/30** (2006.01)

CPC (source: EP)

H05K 3/222 (2013.01); **H05K 7/06** (2013.01); **H05K 3/301** (2013.01); **H05K 3/305** (2013.01); **H05K 2201/10287** (2013.01)

Citation (search report)

- FR 2304247 A1 19761008 - COMMISSARIAT ENERGIE ATOMIQUE [FR]
- DE 3408345 A1 19850912 - SIEMENS AG [DE]
- DE 3408338 A1 19850912 - SIEMENS AG [DE]
- See references of WO 8700721A1

Designated contracting state (EPC)

DE FR GB NL SE

DOCDB simple family (publication)

WO 8700721 A1 19870129; CA 1260157 A 19890926; EP 0231363 A1 19870812; EP 0231363 A4 19880823

DOCDB simple family (application)

US 8601656 W 19860724; CA 514409 A 19860722; EP 86905112 A 19860724